

Combine Type Connector (for SD Memory Card, MultiMediaCard™, MultiMediaCard Plus™, Memory Stick™, xD-Picture Card™)

SCDG Series



New generation 5-in-1 for MultiMediaCard Plus™

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Applicable to four memory card standards - SD Memory Card, MultiMediaCard™, MultiMediaCard Plus™, Memory Stick™ and xD-Picture Card™.
- Push-push ejection mechanism applied in both card types.

Applications

- For desktop PCs, notebook PCs, various personal digital assistants, digital still cameras, digital camcorders, digital photo frames, facsimile machines and printers.
- For home audio equipment (TVs and set top boxes)
- For audio systems
- For headphone players

Typical Specifications

Items		Specifications	
Structure	Applicable media	SD Memory Card	
		MultiMediaCard™	
		MultiMediaCard Plus™	
		Memory Stick™	
		xD-Picture Card™	
Mounting type	Surface mounting type		
Mounting style	Standard mount / Reverse mount		
Media ejection structure	Push-push type		
Performance	Operating temperature range	-10°C to +60°C	
	Voltage proof	250V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	150mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	5,000cycles		

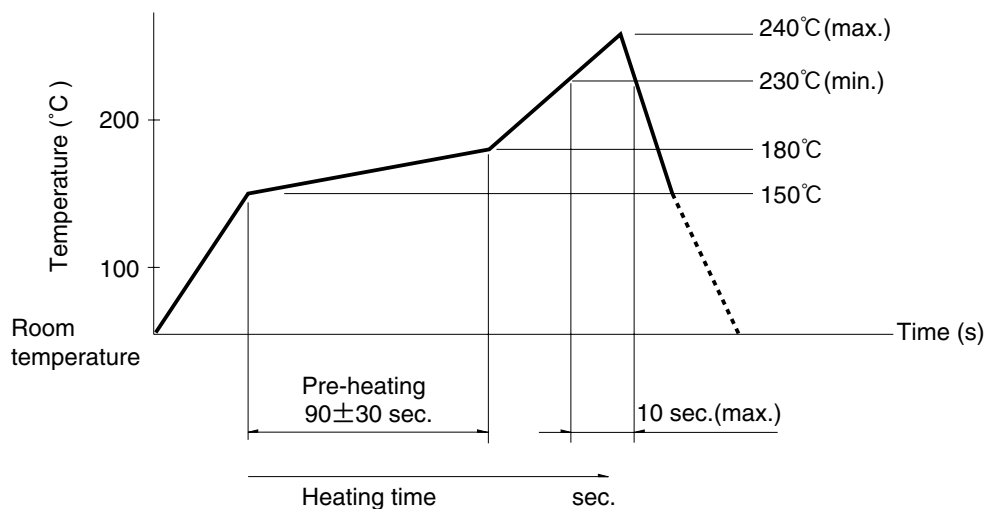
Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	0	Taping	SCDG1A0101	1
	Reverse mount			SCDG2A0101	2

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module